

DELIVERY SPECIFICATION

SPEC. No.
D A T E : Sep., 2025

To

Non-Controlled Copy

CUSTOMER'S PRODUCT NAME	TDK'S PRODUCT NAME MULTILAYER CERAMIC CHIP CAPACITORS High Voltage Series(Soft Termination) Tape packaging 【RoHS2 compliant】 C3225,C4520,C4532 type C0G,X7R Characteristics
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Please return this specification to TDK representatives with your signature.
If orders are placed without returned specification, please allow us to judge that specification is accepted by your side.

RECEIPT CONFIRMATION

DATE: YEAR MONTH DAY

TDK Corporation
Sales
Electronic Components
Sales & Marketing Group

Engineering
Electronic Components Business Company
Ceramic Capacitors Business Group

APPROVED	Person in charge	APPROVED	CHECKED	Person in charge

SCOPE

This delivery specification shall be applied to Multilayer ceramic chip capacitors(Soft Termination Electrode) to be delivered to _____.

PRODUCTION PLACES

Production places defined in this specification shall be TDK Corporation, TDK(Suzhou)Co.,Ltd and TDK Components U.S.A.,Inc.

PRODUCT NAME

The name of the product to be defined in this specifications shall be C◇◇◇◇○○○△△□□□T◎※※※S.

REFERENCE STANDARD

JIS C 5101 – 1 : 2010	Fixed capacitors for use in electronic equipment-Part 1: Generic specification
C 5101 – 21 : 2014	Fixed capacitors for use in electronic equipment-Part 21 : Sectional specification : Fixed surface mount multilayer capacitors of ceramic dielectric,Class1
C 5101 – 22 : 2014	Fixed capacitors for use in electronic equipment-Part 22 : Sectional specification : Fixed surface mount multilayer capacitors of ceramic dielectric,Class2
C 0806 – 3 : 2014	Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes
JEITA RCR – 2335 C 2014	Safety application guide for fixed ceramic capacitors for use in electronic equipment

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<EXPLANATORY NOTE>

When the mistrust in the spec arises, this specification is given priority. And it will be confirmed by written spec change after conference of both posts involved.

This specification warrants the quality of the ceramic chip capacitor. Capacitors should be evaluated or confirmed a state of mounted on your product.

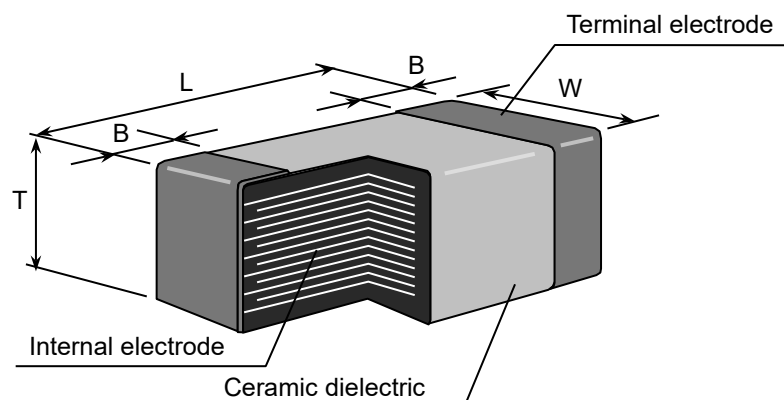
If the use of the capacitors goes beyond the bounds of this specification, we can not afford to guarantee.

Division	Date	SPEC. No.
Ceramic Capacitors Business Group	September, 2024	

1. CODE CONSTRUCTION

(Example) C4532 X7R 3D 222 K T ※※※S
 (1) (2) (3) (4) (5) (6) (7)

(1) Case size



Case size TDK[EIA style]	Dimensions (mm)			
	L	W	T	B
C3225 [CC1210]	3.20 ^{+0.50} _{-0.40}	2.50±0.30	2.00 ^{+0.30} _{-0.20}	0.20 min.
			2.30 ^{+0.30} _{-0.20}	
C4520 [CC1808]	4.50 ^{+0.50} _{-0.40}	2.00 ^{+0.30} _{-0.20}	1.30±0.20	0.20 min.
C4532 [CC1812]	4.50 ^{+0.50} _{-0.40}	3.20±0.40	1.30±0.20	0.20 min.
			2.50±0.30	

* As for each item, please refer to detail page on TDK web.

(2) Temperature Characteristics

* Details are shown in table 1 No.6 and No.7 at 7.PERFORMANCE

(3) Rated Voltage

Symbol	Rated Voltage
3 F	DC 3kV
3 D	DC 2kV
3 A	DC 1kV

(4) Rated Capacitance

Stated in three digits and in units of pico farads (pF).
 The first and Second digits identify the first and second significant figures of the capacitance, the third digit identifies the multiplier.

(Example)

Symbol	Rated Capacitance
222	2,200 pF

(5) Capacitance tolerance

Symbol	Tolerance
J	± 5 %
K	± 10 %

(6) Packaging

Symbol	Packaging
T	Taping

(7) TDK internal code

※※※ S
└─ S : Soft Termination
└─ These TDK internal codes are subject to change without notice.

2. COMBINATION OF RATED CAPACITANCE AND TOLERANCE

Class	Temperature Characteristics	Capacitance tolerance	Rated capacitance
1	C0G	J ($\pm 5\%$) K ($\pm 10\%$)	E – 12 series
2	X7R	K ($\pm 10\%$)	E – 3 series

Capacitance Step in E series

E series	Capacitance Step											
E-3	1.0				2.2				4.7			
E-12	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2

3. OPERATING TEMPERATURE RANGE

Min. operating Temperature	Max. operating Temperature	Reference Temperature
-55°C	125°C	25°C

4. STORING CONDITION AND TERM

Storing temperature	Storing humidity	Storing term
5~40°C	20~70%RH	Within 6 months upon receipt.

5. P.C. BOARD

When mounting on an aluminum substrate, it is more likely to be affected by heat stress from the substrate.

Please inquire separate specification for the large case sizes when mounted on the substrate.

6. INDUSTRIAL WASTE DISPOSAL

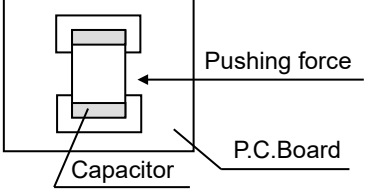
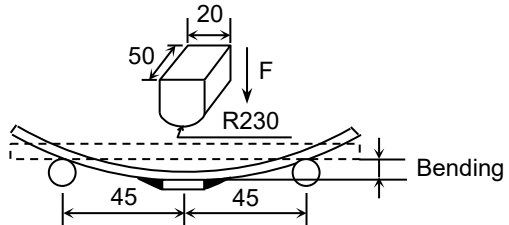
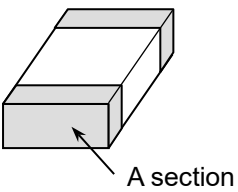
Dispose this product as industrial waste in accordance with the Industrial Waste Law.

7. PERFORMANCE

table 1

No.	Item		Performance	Test or inspection method																				
1	External Appearance		No defects which may affect performance.	Inspect with magnifying glass (3×)																				
2	Insulation Resistance		10,000MΩ min.	Measuring voltage : 500V DC Voltage application time : 60s.																				
3	Voltage Proof		Withstand test voltage without insulation breakdown or other damage.	Applied voltage : 1.2 times of rated voltage Voltage application time : 1s. Charge / discharge current : 50mA or lower																				
4	Capacitance		Within the specified tolerance.	<table><tr><td colspan="3">《Class 1》</td></tr><tr><td>Capacitance</td><td>Measuring frequency</td><td>Measuring voltage</td></tr><tr><td>1,000pF and under</td><td>1MHz±10%</td><td rowspan="2">0.5~5 Vrms.</td></tr><tr><td>Over 1,000pF</td><td>1kHz±10%</td></tr><tr><td colspan="3">《Class 2》</td></tr><tr><td colspan="2">Measuring frequency</td><td>Measuring voltage</td></tr><tr><td colspan="2">1kHz±10%</td><td>1.0±0.2 Vrms.</td></tr></table>	《Class 1》			Capacitance	Measuring frequency	Measuring voltage	1,000pF and under	1MHz±10%	0.5~5 Vrms.	Over 1,000pF	1kHz±10%	《Class 2》			Measuring frequency		Measuring voltage	1kHz±10%		1.0±0.2 Vrms.
《Class 1》																								
Capacitance	Measuring frequency	Measuring voltage																						
1,000pF and under	1MHz±10%	0.5~5 Vrms.																						
Over 1,000pF	1kHz±10%																							
《Class 2》																								
Measuring frequency		Measuring voltage																						
1kHz±10%		1.0±0.2 Vrms.																						
5	Q	Class1	Please refer to detail page on TDK web.	See No.4 in this table for measuring condition.																				
	Dissipation Factor	Class2																						
6	Temperature Characteristics of Capacitance (Class1)		<table><tr><td>T.C.</td><td>Temperature Coefficient (ppm/°C)</td></tr><tr><td>C0G</td><td>0 ± 30</td></tr></table> <table><tr><td>Capacitance drift</td><td>Within ± 0.2%.</td></tr></table>	T.C.	Temperature Coefficient (ppm/°C)	C0G	0 ± 30	Capacitance drift	Within ± 0.2%.	Temperature coefficient shall be calculated based on values at 25°C and 85°C temperature. Measuring temperature below 25°C shall be -10°C and -25°C.														
T.C.	Temperature Coefficient (ppm/°C)																							
C0G	0 ± 30																							
Capacitance drift	Within ± 0.2%.																							
7	Temperature Characteristics of Capacitance (Class2)		<table><tr><td>Capacitance Change (%)</td></tr><tr><td>No voltage applied</td></tr><tr><td>X7R : ±15</td></tr></table>	Capacitance Change (%)	No voltage applied	X7R : ±15	<table><tr><td>Step</td><td>Temperature(°C)</td></tr><tr><td>1</td><td>Reference temp. ± 2</td></tr><tr><td>2</td><td>Min. operating temp. ± 2</td></tr><tr><td>3</td><td>Reference temp. ± 2</td></tr><tr><td>4</td><td>Max. operating temp. ± 2</td></tr></table> <p>Capacitance shall be measured by the steps shown in the following table after thermal equilibrium is obtained for each step. ΔC be calculated ref. STEP3 reading</p> <p>As for Min./Max. operating temp and Reference temp., please refer to “3. OPERATING TEMPERATURE RANGE” As for measuring voltage, please contact with our sales representative.</p>	Step	Temperature(°C)	1	Reference temp. ± 2	2	Min. operating temp. ± 2	3	Reference temp. ± 2	4	Max. operating temp. ± 2							
Capacitance Change (%)																								
No voltage applied																								
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Step	Temperature(°C)																							
1	Reference temp. ± 2																							
2	Min. operating temp. ± 2																							
3	Reference temp. ± 2																							
4	Max. operating temp. ± 2																							

(continued)

No.	Item		Performance	Test or inspection method
8	Robustness of Terminations		No sign of termination coming off, breakage of ceramic, or other abnormal signs.	<p>Reflow solder the capacitors on a P.C.Board shown in Appendix 2.</p> <p>Apply a pushing force gradually at the center of a specimen in a horizontal direction of P.C.board.</p> <p>Pushing force : 5N</p> <p>Holding time : 10±1s</p> 
9	Bending	External appearance	No mechanical damage.	<p>Reflow solder the capacitors on a P.C.Board shown in Appendix 1 and bend it for 5mm. (2mm is applied for C4520 and C4532.)</p>  <p>(Unit : mm)</p>
10	Solderability		<p>New solder to cover over 75% of termination.</p> <p>25% may have pin holes or rough spots but not concentrated in one spot.</p> <p>Ceramic surface of A sections shall not be exposed due to melting or shifting of termination material.</p> 	<p>Solder : Sn-3.0Ag-0.5Cu</p> <p>Flux : Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.</p> <p>Solder temp. : 245±5°C</p> <p>Dwell time : 3±0.3s.</p> <p>Solder position : Until both terminations are completely soaked.</p>

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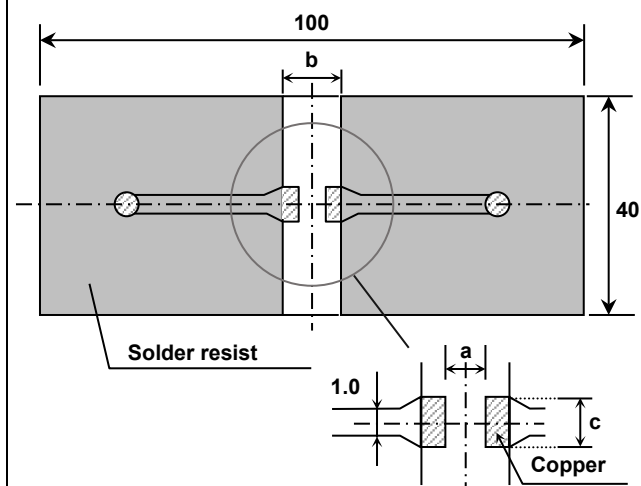
No.	Item		Performance		Test or inspection method			
11	Resistance to solder heat	External appearance	No cracks are allowed and terminations shall be covered at least 60% with new solder.		Solder : Sn-3.0Ag-0.5Cu			
		Capacitance	Characteristics		Change from the value before test	Flux : Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.		
			Class 1	C0G	± 2.5 %	Solder temp. : 260±5°C		
			Class 2	X7R	± 7.5 %	Dwell time : 10±1s.		
			Q (Class1)	Meet the initial spec.		Solder position : Until both terminations are completely soaked.		
		D.F. (Class2)	Meet the initial spec.		Pre-heating : Temp. — 110~140°C Time — 30~60s.			
		Insulation Resistance	Meet the initial spec.		Leave the capacitors in ambient condition for			
	Voltage proof	No insulation breakdown or other damage.		Class 1 : 6~24h Class 2 : 24±2h before measurement.				
12	Vibration	External appearance	No mechanical damage.		Frequency : 10~55~10Hz			
		Capacitance	Characteristics		Change from the value before test	Reciprocating sweep time : 1 min.		
			Class 1	C0G	± 2.5 %	Amplitude : 1.5mm		
			Class 2	X7R	± 7.5 %	Repeat this for 2h each in 3 perpendicular directions(Total 6h).		
		Q (Class1)	Meet the initial spec.		Reflow solder the capacitors on a P.C.Board shown in Appendix 2 before testing.			
	D.F. (Class2)	Meet the initial spec.						
13	Temperature Cycle	External appearance	No mechanical damage.		Expose the capacitors in the condition step1 through step 4 listed in the following table.			
		Capacitance	Characteristics		Change from the value before test	Temp. cycle : 5 cycles		
			Class 1	C0G	Please contact with our sales representative.	Step	Temperature(°C)	Time (min.)
			Class 2	X7R		1	Min. operating temp.±3	30 ± 3
		Q (Class1)	Meet the initial spec.		2	Ambient Temp.	2 ~ 5	
		D.F. (Class2)	Meet the initial spec.		3	Max. operating temp.±2	30 ± 2	
		Insulation Resistance	Meet the initial spec.		4	Ambient Temp.	2 ~ 5	
	Voltage proof	No insulation breakdown or other damage.		As for Min./Max. operating temp., please refer to “3. OPERATING TEMPERATURE RANGE”				
				Leave the capacitors in ambient condition for				
				Class 1 : 6~24h Class 2 : 24±2h before measurement.				
				Reflow solder the capacitors on a P.C.Board shown in Appendix 2 before testing.				

(continued)

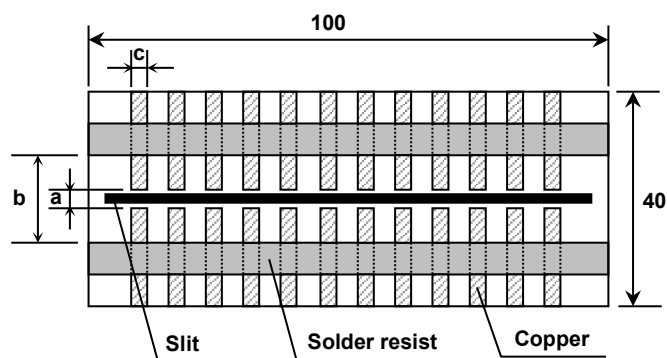
No.	Item		Performance		Test or inspection method								
14	Moisture Resistance (Steady State)	External appearance	No mechanical damage.		Test temp. : 40±2°C Test humidity : 90~95%RH Test time : 500 +24,0h								
		Capacitance	<table><tr><td colspan="2">Characteristics</td><td>Change from the value before test</td></tr><tr><td>Class 1</td><td>C0G</td><td rowspan="2">Please contact with our sales representative.</td></tr><tr><td>Class 2</td><td>X7R</td></tr></table>		Characteristics		Change from the value before test	Class 1	C0G	Please contact with our sales representative.	Class 2	X7R	Leave the capacitors in ambient condition for Class 1 : 6~24h Class 2 : 24±2h before measurement.
		Characteristics		Change from the value before test									
		Class 1	C0G	Please contact with our sales representative.									
		Class 2	X7R										
Q (Class1)	350 min.		Reflow solder the capacitors on a P.C.Board shown in Appendix 2 before testing.										
D.F. (Class2)	200% of initial spec. max.												
Insulation Resistance	1,000MΩ min.												
15	Life	External appearance	No mechanical damage.		Test temp. : Maximum operating temperature±2°C Applied voltage : Please contact with our sales representative. Test time : 1,000 +48,0h Charge/discharge current : 50mA or lower								
		Capacitance	<table><tr><td colspan="2">Characteristics</td><td>Change from the value before test</td></tr><tr><td>Class 1</td><td>C0G</td><td rowspan="2">Please contact with our sales representative.</td></tr><tr><td>Class 2</td><td>X7R</td></tr></table>		Characteristics		Change from the value before test	Class 1	C0G	Please contact with our sales representative.	Class 2	X7R	Leave the capacitors in ambient condition for Class 1 : 6~24h Class 2 : 24±2h before measurement.
		Characteristics		Change from the value before test									
		Class 1	C0G	Please contact with our sales representative.									
		Class 2	X7R										
Q (Class1)	350 min.		Reflow solder the capacitors on a P.C.Board shown in Appendix 2 before testing.										
D.F. (Class2)	200% of initial spec. max.												
Insulation Resistance	1,000MΩ min.			Initial value setting (only for class 2) Voltage conditioning 《After voltage treat the capacitors under testing temperature and voltage for 1 hour,》 leave the capacitors in ambient condition for 24±2h before measurement. Use this measurement for initial value.									

*As for the initial measurement of capacitors (Class2) on number 7,11,12,13 and 14, leave capacitors at 150 -10,0°C for 1 hour and measure the value after leaving capacitors for 24±2h in ambient condition.

Appendix1 P.C.Board for bending test



Appendix2 P.C. Board for reliability test





(Unit : mm)

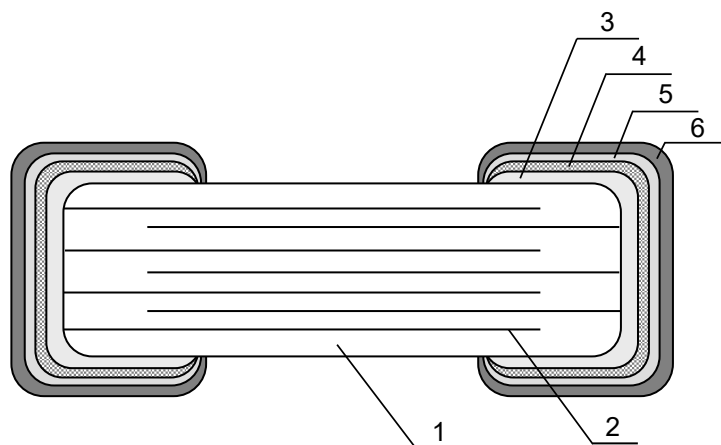
Symbol	a	b	c
Case size			
C3225 [CC1210]	2.2	5.0	2.9
C4520 [CC1808]	3.5	7.0	2.5
C4532 [CC1812]	3.5	7.0	3.7

1. Material : Glass Epoxy(As per JIS C6484 GE4)

2. Thickness : 1.6mm

 Copper(Thickness:0.035mm)
 Solder resist

8. INSIDE STRUCTURE AND MATERIAL



No.	NAME	MATERIAL	
		Class1	Class2
1	Dielectric	CaZrO ₃	BaTiO ₃
2	Electrode	Nickel (Ni)	
3	Termination	Copper (Cu)	
4		Conductive resin (Filler : Ag)	
5		Nickel (Ni)	
6		Tin (Sn)	

9. CAUTION FOR PRODUCTS WITH SOFT TERMINATION

This product contains Ag (Silver) as part of the middle layer of termination.

To avoid electromigration of Ag under high temperature and humidity, and failures caused by corrosive gas, chip capacitors on P.C boards should be protected by moisture proof-sealing.

10. PACKAGING

Packaging shall be done to protect the components from the damage during transportation and storing, and a label which has the following information shall be attached.

Tape packaging is as per 14. TAPE PACKAGING SPECIFICATION.

1) Inspection No.*

2) TDK P/N

3) Customer's P/N

4) Quantity

*Composition of Inspection No.

Example F 5 A - 23 - 001
 (a) (b) (c) (d) (e)

(a) Line code

(b) Last digit of the year

(c) Month and A for January and B for February and so on. (Skip I)

(d) Inspection Date of the month.

(e) Serial No. of the day

*Composition of new Inspection No.

(Implemented on and after May 1, 2019 in sequence)

Example

I	F	5	E	2	3	A	0	0	1
---	---	---	---	---	---	---	---	---	---

 (a) (b) (c) (d) (e) (f) (g)

(a) Prefix

(b) Line code

(c) Last digit of the year

(d) Month and A for January and B for February and so on. (Skip I)

(e) Inspection Date of the month.

(f) Serial No. of the day(00 ~ ZZ)

(g) Suffix(00 ~ ZZ)

*It was shifted to the new inspection No. on and after May 2019, but the implementation timing may be different depending on shipment bases.

Until the shift is completed, either current or new composition of inspection No. will be applied.

11. RECOMMENDATION


It is recommended to provide a slit (about 1mm width) in the board under the components to improve washing flux. And please make sure to dry detergent up completely before.

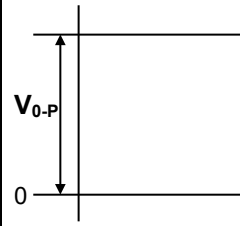
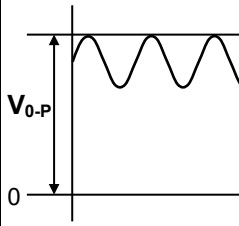
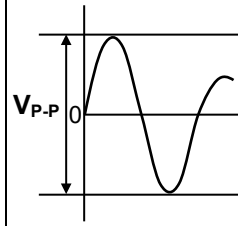
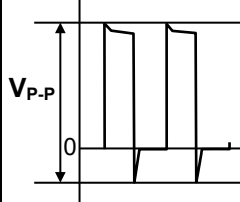
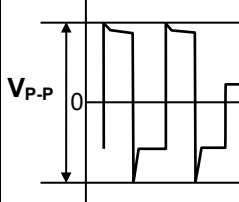
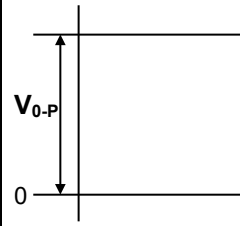
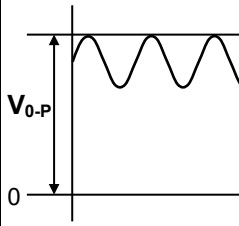
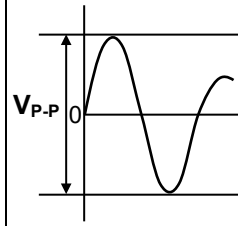
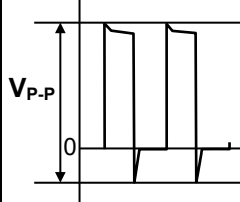
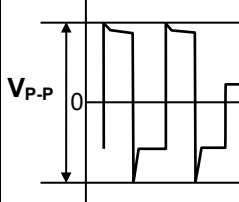
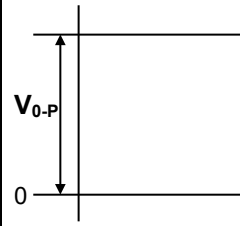
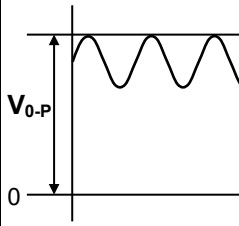
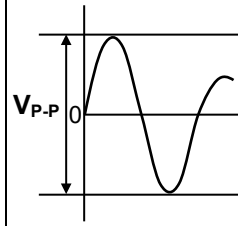
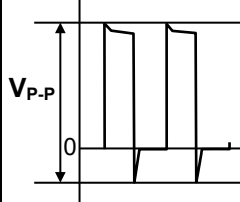
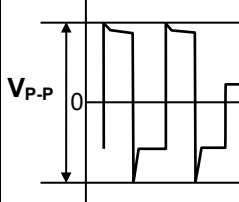
It is recommended to use low activated flux (Chlorine content : less than 0.1wt%) such Rosin due to high voltage usage.

12. SOLDERING CONDITION

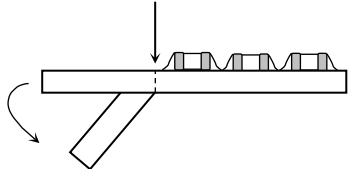
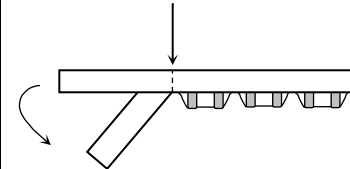
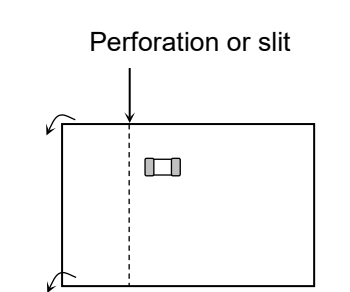
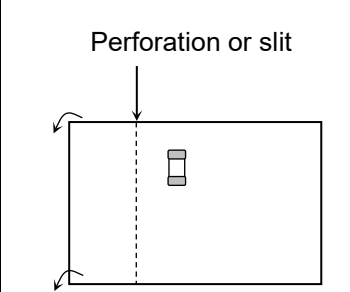
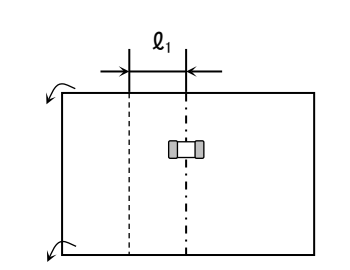
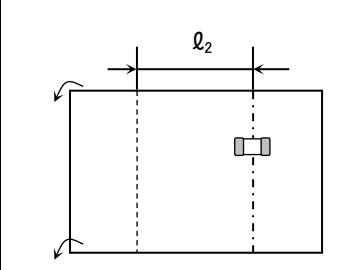
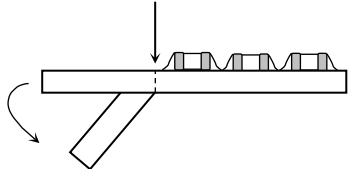
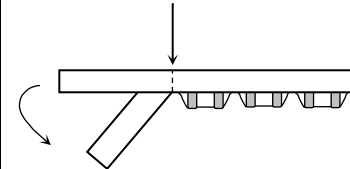
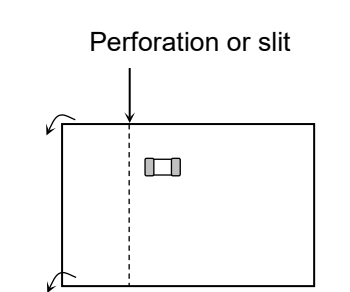
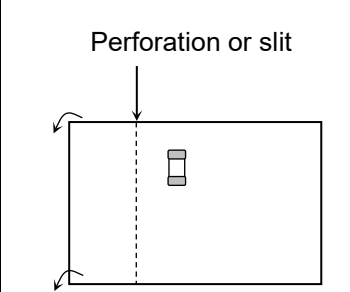
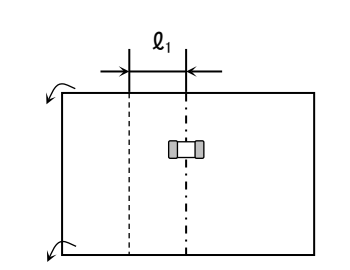
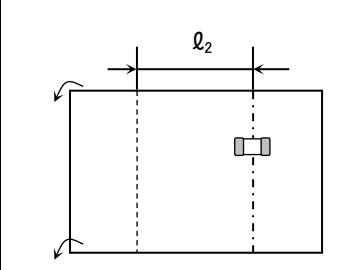
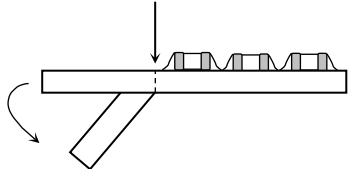
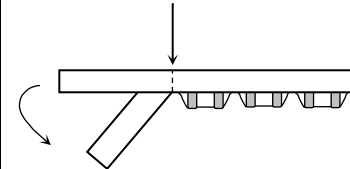
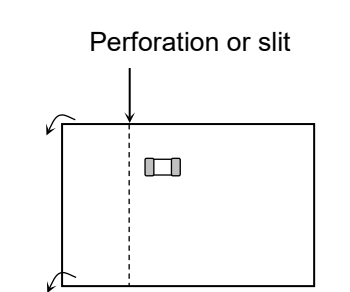
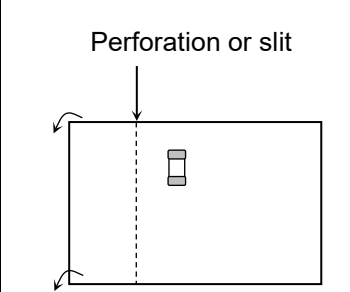
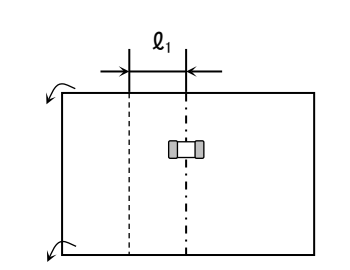
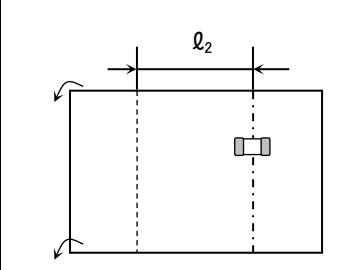
Reflow soldering only.

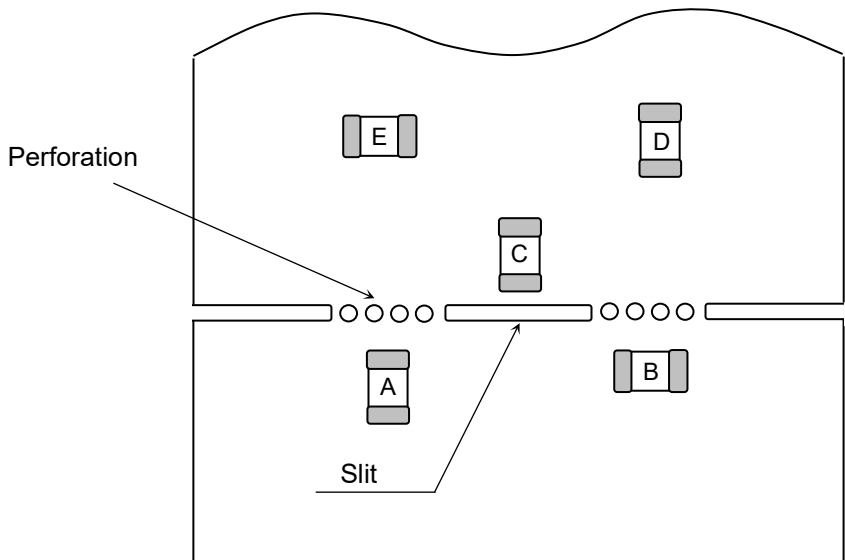
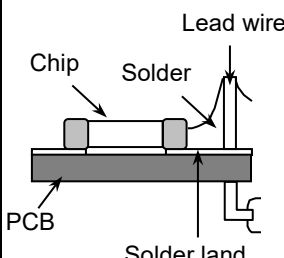
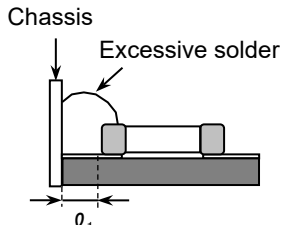
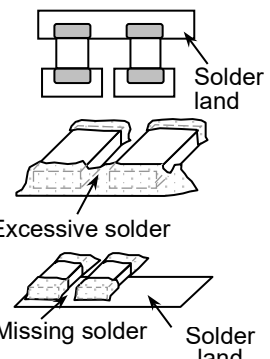
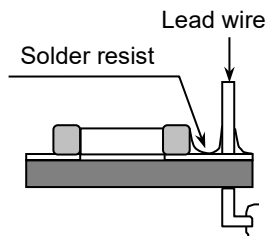
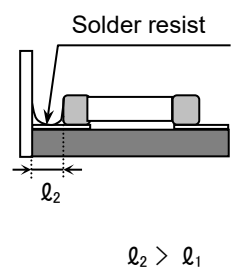
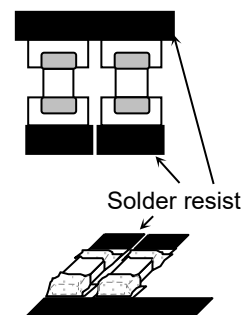
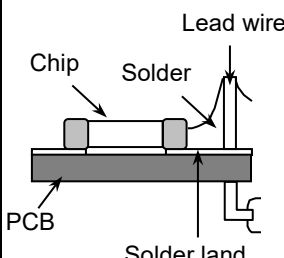
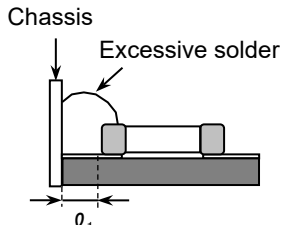
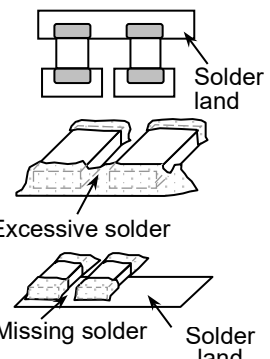
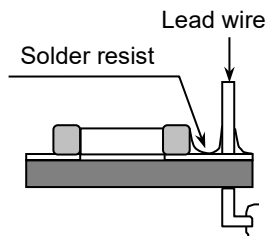
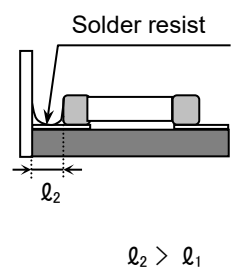
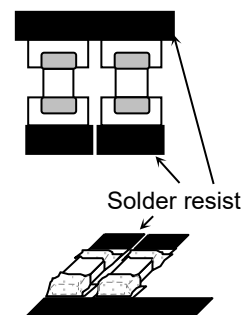
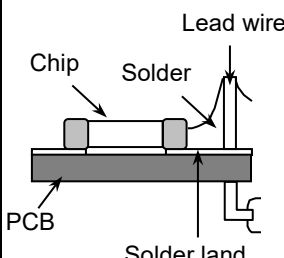
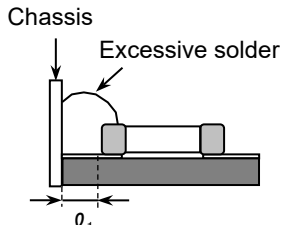
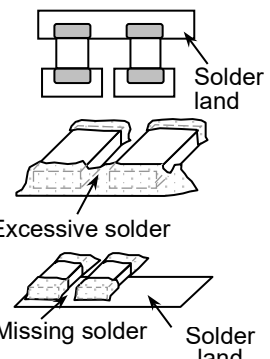
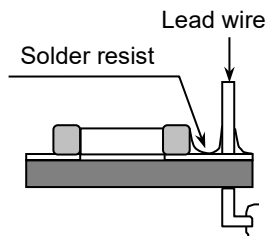
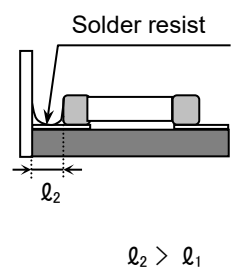
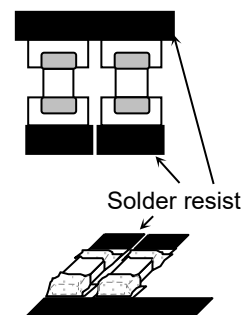
13. CAUTION

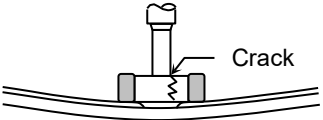
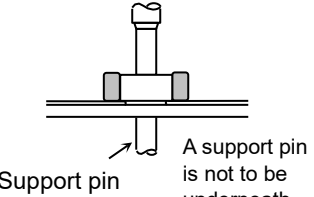
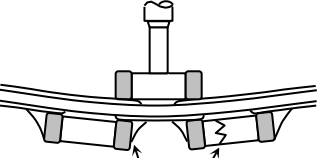
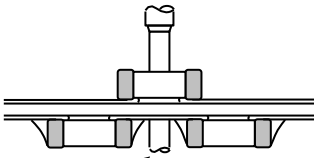
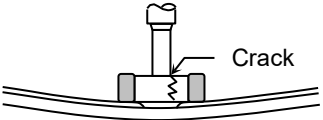
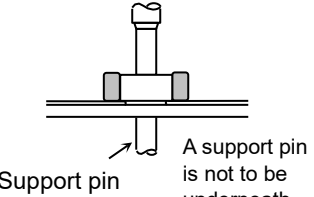
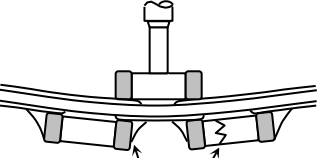
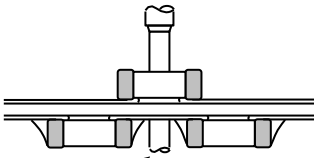
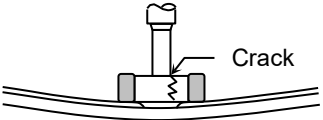
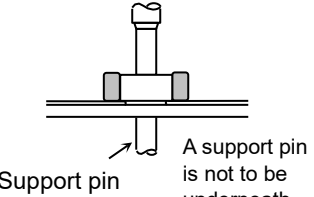
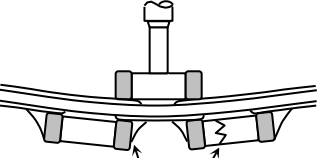
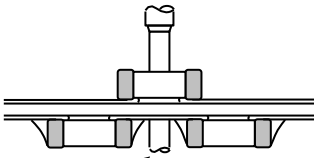
No.	Process	Condition
1	Operating Condition (Storage, Use, Transportation)	<p>1-1. Storage, Use The capacitors must be stored in an ambient temperature of 5 to 40°C with a relative humidity of 20 to 70%RH. JIS C 60721-3-1 Class 1K2 should be followed for the other climatic conditions.</p> <p>1) High temperature and humidity environment may affect a capacitor's solder ability because it accelerates terminal oxidization. They also deteriorate performance of taping and packaging. Therefore, SMD capacitors shall be used within 6 months. For capacitors with terminal electrodes consisting of silver or silver-palladium which tend to become oxidized or sulfurized, use as soon as possible, such as within one month after opening the bag.</p> <p>2) When capacitors are stored for a longer time period than 6 months, confirm the solderability of the capacitors prior to use. During storage, keep the minimum packaging unit in its original packaging without opening it. Do not deviate from the above temperature and humidity conditions even for a short term.</p> <p>3) Corrosive gasses in the air or atmosphere may result in deterioration of the reliability, such as poor solderability of the terminal electrodes. Do not store capacitors where they will be exposed to corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine ammonia etc.)</p> <p>4) Solderability and electrical performance may deteriorate due to photochemical change in the terminal electrode if stored in direct sunlight, or due to condensation from rapid changes in humidity. The capacitors especially which use resin material must be operated and stored in an environment free of dew condensation, as moisture absorption due to condensation may affect the performance.</p> <p>5) Refer to JIS C 60721-3-1, class 1K2 for other climate conditions.</p> <p>1-2. Handling in transportation</p> <p>1) In case of the transportation of the capacitors, the performance of the capacitors may be deteriorated depending on the transportation condition. (Refer to JEITA RCR-2335C 9.2 Handling in transportation)</p>
2	Circuit design  Caution	<p>2-1. Operating temperature Operating temperature should be followed strictly within this specification, especially be careful with maximum temperature.</p> <p>1) Upper category temperature (maximum operating temperature) is specified. It is necessary to select a capacitor whose rated temperature is higher than the operating temperature. Also, it is necessary to consider the temperature distribution in the equipment and seasonal temperature variation.</p> <p>2) Surface temperature including self heating should be below maximum operating temperature. Due to dielectric loss, capacitors will heat itself when AC is applied due to ESR. Especially at high frequencies, please be careful that the heat might be so extreme. Also, even if the surface temperature of the capacitor includes self-heating and is the maximum operating temperature or lower, excessive heating of the capacitor due to self-heating may cause deterioration of the characteristics and reliability of the capacitor. The self-heating temperature rise of the capacitor changes depending on the difference in heat radiation due to the mounting method to the device, the ambient temperature, the cooling method of the device and circuit board material and the design, etc. The load should be contained so that the self-heating temperature rise of the capacitor body in a natural convection environment at an ambient temperature of 25°C remain below 20°C. When using in a high-frequency circuit or a circuit in which a capacitor generates heat, such as when a high-frequency ripple current flows, pay attention to the above precautions. (Note that accurate measurement may not be possible with self-heating measurement when the equipment applies cooling other than natural convection such as a cooling fan.)</p> <p>3) The electrical characteristics of the capacitors will vary depending on the temperature. The capacitors should be selected and designed in taking the temperature into consideration.</p>

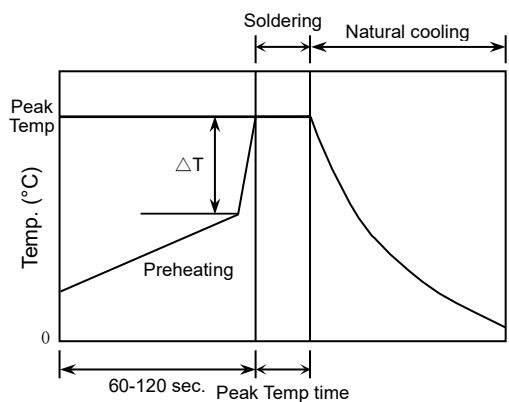
No.	Process	Condition														
2	Circuit design ⚠ Caution	<p>2-2. When overvoltage is applied</p> <p>Applying overvoltage to a capacitor may cause dielectric breakdown and result in a short circuit. The duration until dielectric breakdown depends on the applied voltage and the ambient temperature.</p> <p>2-3. Operating voltage</p> <p>1) Operating voltage across the terminals should be below the rated voltage. When AC and DC are super imposed, V_{0-P} must be below the rated voltage. — (1) and (2)</p> <p>AC or pulse with overshooting, V_{P-P} must be below the rated voltage. — (3), (4) and (5)</p> <p>When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use the capacitors within rated voltage containing these Irregular voltage.</p> <table><tr><th>Voltage</th><th>(1) DC voltage</th><th>(2) DC+AC voltage</th><th>(3) AC voltage</th></tr><tr><td>Positional Measurement (Rated voltage)</td><td></td><td></td><td></td></tr></table> <table><tr><th>Voltage</th><th>(4) Pulse voltage (A)</th><th>(5) Pulse voltage (B)</th></tr><tr><td>Positional Measurement (Rated voltage)</td><td></td><td></td></tr></table> <p>2) Even below the rated voltage, if repetitive high frequency AC or pulse is applied, the reliability of the capacitors may be reduced.</p> <p>3) The effective capacitance will vary depending on applied DC and AC voltages. The capacitors should be selected and designed in taking the voltages into consideration.</p> <p>4) Abnormal voltage (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated voltage.</p> <p>5) When capacitors are used in a series connection, it is necessary to add a balancing circuit such as voltage dividing resistors in order to avoid an imbalance in the voltage applied to each capacitor.</p> <p>2-4. Frequency</p> <p>When the capacitors (Class 2) are used in AC and/or pulse voltages, the capacitors may vibrate themselves and generate audible sound.</p>	Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage	Positional Measurement (Rated voltage)				Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)	Positional Measurement (Rated voltage)		
Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage													
Positional Measurement (Rated voltage)																
Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)														
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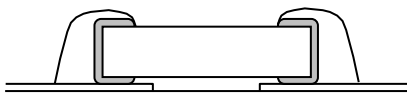
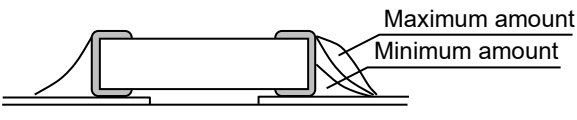
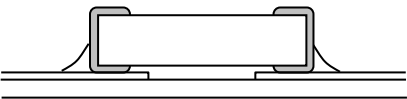
No.	Process	Condition																				
3	Designing P.C.board	<p>The amount of solder at the terminations has a direct effect on the reliability of the capacitors.</p> <ol style="list-style-type: none"> 1) The greater the amount of solder, the higher the stress on the chip capacitors, and the more likely that it will break. When designing a P.C.board, determine the shape and size of the solder lands to have proper amount of solder on the terminations. 2) Avoid using common solder land for multiple terminations and provide individual solder land for each terminations. 3) Size and recommended land dimensions. <div> </div> <p>Reflow soldering</p> <div> <div>(Unit : mm)</div> <table> <tr> <th>Case size Symbol</th> <th>C3225 [CC1210]</th> <th>C4520 [CC1808]</th> <th>C4532 [CC1812]</th> </tr> <tr> <td>A</td> <td>2.0 ~ 2.4</td> <td>3.1 ~ 3.7</td> <td>3.1 ~ 3.7</td> </tr> <tr> <td>B</td> <td>1.0 ~ 1.2</td> <td>1.2 ~ 1.4</td> <td>1.2 ~ 1.4</td> </tr> <tr> <td>C</td> <td>1.9 ~ 2.5</td> <td>1.5 ~ 2.0</td> <td>2.4 ~ 3.2</td> </tr> <tr> <td>D</td> <td>1.0 ~ 1.3</td> <td>1.0 ~ 1.3</td> <td>1.0 ~ 1.3</td> </tr> </table> </div> <ol style="list-style-type: none"> 4) It is recommended to provide a slit (about 1mm width) in the board under the components to improve washing flux. And please make sure to dry detergent up completely before. <p>It is recommended to use low activated flux (Chlorine content : less than 0.1wt%) such Rosin due to high voltage usage.</p>	Case size Symbol	C3225 [CC1210]	C4520 [CC1808]	C4532 [CC1812]	A	2.0 ~ 2.4	3.1 ~ 3.7	3.1 ~ 3.7	B	1.0 ~ 1.2	1.2 ~ 1.4	1.2 ~ 1.4	C	1.9 ~ 2.5	1.5 ~ 2.0	2.4 ~ 3.2	D	1.0 ~ 1.3	1.0 ~ 1.3	1.0 ~ 1.3
Case size Symbol	C3225 [CC1210]	C4520 [CC1808]	C4532 [CC1812]																			
A	2.0 ~ 2.4	3.1 ~ 3.7	3.1 ~ 3.7																			
B	1.0 ~ 1.2	1.2 ~ 1.4	1.2 ~ 1.4																			
C	1.9 ~ 2.5	1.5 ~ 2.0	2.4 ~ 3.2																			
D	1.0 ~ 1.3	1.0 ~ 1.3	1.0 ~ 1.3																			

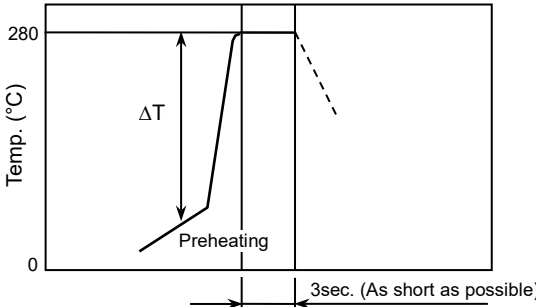
No.	Process	Condition												
3	Designing P.C.board	<p>5) Recommended chip capacitors layout is as following.</p> <table> <tr> <th></th><th>Disadvantage against bending stress</th><th>Advantage against bending stress</th></tr> <tr> <th>Mounting face</th><td> <p>Perforation or slit</p>  <p>Break P.C.board with mounted side up.</p> </td><td> <p>Perforation or slit</p>  <p>Break P.C.board with mounted side down.</p> </td></tr> <tr> <th>Chip arrangement (Direction)</th><td> <p>Mount perpendicularly to perforation or slit</p>  </td><td> <p>Mount in parallel with perforation or slit</p>  </td></tr> <tr> <th>Distance from slit</th><td> <p>Closer to slit is higher stress</p>  <p>($l_1 < l_2$)</p> </td><td> <p>Away from slit is less stress</p>  <p>($l_1 < l_2$)</p> </td></tr> </table>		Disadvantage against bending stress	Advantage against bending stress	Mounting face	<p>Perforation or slit</p>  <p>Break P.C.board with mounted side up.</p>	<p>Perforation or slit</p>  <p>Break P.C.board with mounted side down.</p>	Chip arrangement (Direction)	<p>Mount perpendicularly to perforation or slit</p> 	<p>Mount in parallel with perforation or slit</p> 	Distance from slit	<p>Closer to slit is higher stress</p>  <p>($l_1 < l_2$)</p>	<p>Away from slit is less stress</p>  <p>($l_1 < l_2$)</p>
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No.	Process	Condition												
3	Designing P.C.board	<div>6) Mechanical stress varies according to location of chip capacitors on the P.C.board.</div> <div><div>Stress force A>B>E A>D>E A>C</div></div> <div>When dividing printed wiring boards, the intensities of mechanical stress applied to capacitors are different according to each dividing method in the order of : Push-back < Slit < V-groove < Perforation. Therefore consider not only position of capacitors, but also the way of the dividing the printed wiring boards.</div> <div>7) Layout recommendation</div> <table><tr><th>Example</th><th>Use of common solder land</th><th>Soldering with chassis</th><th>Use of common solder land with other SMD</th></tr><tr><td>Need to avoid</td><td></td><td></td><td></td></tr><tr><td>Recommendation</td><td></td><td></td><td></td></tr></table> <div>8) When mounting on an aluminum substrate, it is more likely to be affected by heat stress from the substrate. Please inquire separate specification when mounted on the substrate.</div>	Example	Use of common solder land	Soldering with chassis	Use of common solder land with other SMD	Need to avoid				Recommendation			
Example	Use of common solder land	Soldering with chassis	Use of common solder land with other SMD											
Need to avoid														
Recommendation														

No.	Process	Condition									
4	Mounting	<p data-bbox="432 203 1444 309">4-1. Stress from mounting head If the mounting head is adjusted too low, it may induce excessive stress in the chip capacitors to result in cracking. Please take following precautions.</p> <ol data-bbox="432 338 1444 595" style="list-style-type: none"> <li data-bbox="432 338 1444 405">1) Adjust the bottom dead center of the mounting head to reach on the P.C.board surface and not press it. <li data-bbox="432 434 1444 468">2) Adjust the mounting head pressure to be 1 to 3N of static weight. <li data-bbox="432 497 1444 595">3) To minimize the impact energy from mounting head, it is important to provide support from the bottom side of the P.C.board. See following examples. <table data-bbox="475 629 1425 1218"> <tr> <th data-bbox="475 629 660 680"></th><th data-bbox="660 629 1050 680">Not recommended</th><th data-bbox="1050 629 1425 680">Recommended</th></tr> <tr> <td data-bbox="475 680 660 958">Single-sided mounting</td><td data-bbox="660 680 1050 958">  <p data-bbox="927 801 991 831">Crack</p> </td><td data-bbox="1050 680 1425 958">  <p data-bbox="1082 869 1198 898">Support pin</p> <p data-bbox="1267 837 1401 943">A support pin is not to be underneath the capacitor.</p> </td></tr> <tr> <td data-bbox="475 958 660 1218">Double-sides mounting</td><td data-bbox="660 958 1050 1218">  <p data-bbox="735 1151 815 1205">Solder peeling</p> <p data-bbox="847 1160 911 1189">Crack</p> </td><td data-bbox="1050 958 1425 1218">  <p data-bbox="1123 1173 1246 1202">Support pin</p> </td></tr> </table> <p data-bbox="453 1227 1422 1323">When the centering jaw is worn out, it may give mechanical impact on the capacitors to cause crack. Please control the close up dimension of the centering jaw and provide sufficient preventive maintenance and replacement of it.</p>		Not recommended	Recommended	Single-sided mounting	 <p data-bbox="927 801 991 831">Crack</p>	 <p data-bbox="1082 869 1198 898">Support pin</p> <p data-bbox="1267 837 1401 943">A support pin is not to be underneath the capacitor.</p>	Double-sides mounting	 <p data-bbox="735 1151 815 1205">Solder peeling</p> <p data-bbox="847 1160 911 1189">Crack</p>	 <p data-bbox="1123 1173 1246 1202">Support pin</p>
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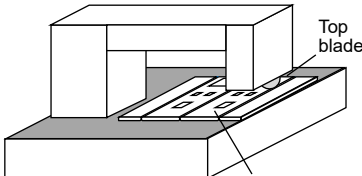
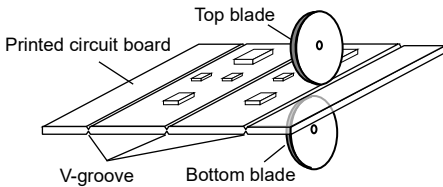
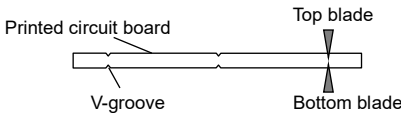
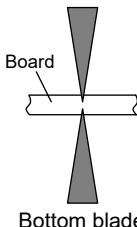
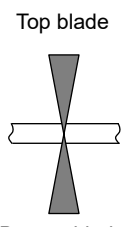
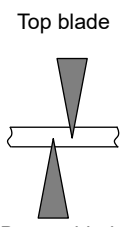
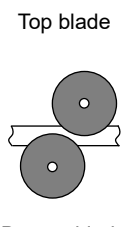
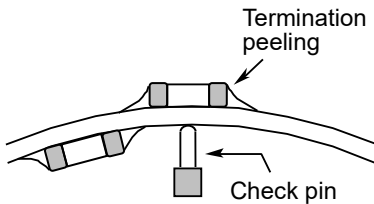
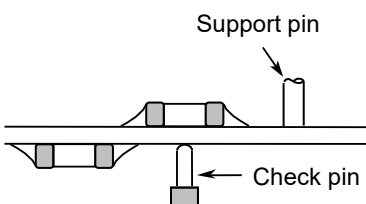
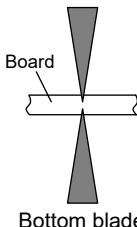
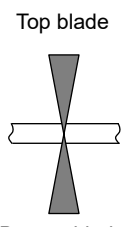
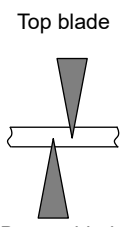
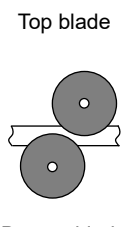
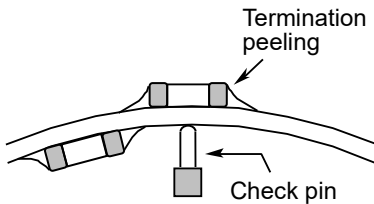
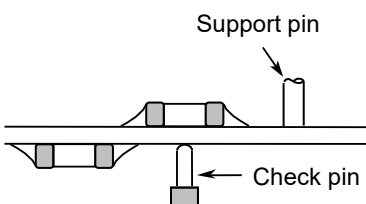
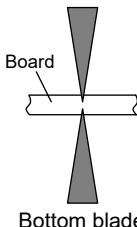
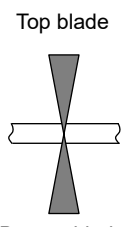
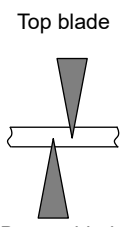
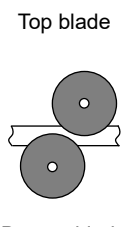
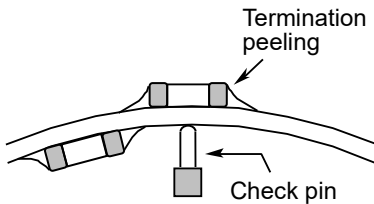
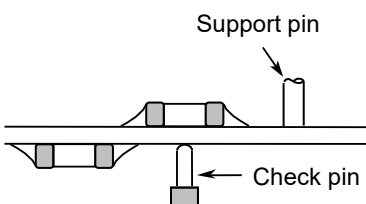
No.	Process	Condition																		
5	Soldering	<div>5-1. Flux selection</div> <div>Flux can seriously affect the performance of capacitors. Confirm the following to select the appropriate flux.</div> <div><div>1) It is recommended to use a mildly activated rosin flux (less than 0.1wt% chlorine). Strong flux is not recommended.</div><div>2) Excessive flux must be avoided. Please provide proper amount of flux.</div><div>3) When water-soluble flux is used, enough washing is necessary.</div></div> <div>5-2. Recommended soldering profile : Reflow method</div> <div>Refer to the following temperature profile at Reflow soldering.</div> <div><div>Flow soldering</div></div> <div>5-3. Recommended soldering peak temp and peak temp duration</div> <table><tr><th rowspan="2">Temp./Duration</th><th colspan="2">Reflow soldering</th></tr><tr><th>Peak temp(°C)</th><th>Duration(sec.)</th></tr><tr><th>Solder</th><td></td><td></td></tr><tr><td>Lead Free Solder</td><td>260 max.</td><td>10 max.</td></tr><tr><td>Sn-Pb Solder</td><td>230 max.</td><td>20 max.</td></tr></table> <div>Recommended solder compositions</div> <div>Lead Free Solder : Sn-3.0Ag-0.5Cu</div> <div>5-4. Avoiding thermal shock</div> <div><div>1) Preheating condition</div><table><tr><th>Soldering</th><th>Temp. (°C)</th></tr><tr><td>Reflow soldering</td><td>$\Delta T \leq 130$</td></tr></table></div> <div><div>2) Cooling condition</div><div>Natural cooling using air is recommended. If the chips are dipped into a solvent for cleaning, the temperature difference (ΔT) must be less than 100°C.</div></div>	Temp./Duration	Reflow soldering		Peak temp(°C)	Duration(sec.)	Solder			Lead Free Solder	260 max.	10 max.	Sn-Pb Solder	230 max.	20 max.	Soldering	Temp. (°C)	Reflow soldering	$\Delta T \leq 130$
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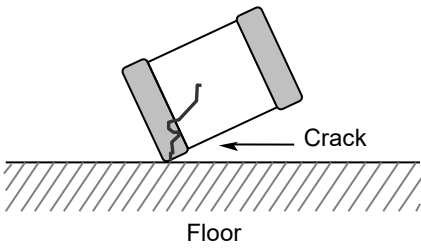
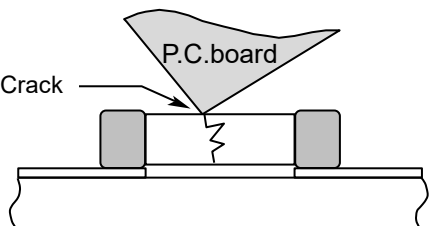
No.	Process	Condition
5	Soldering	<p data-bbox="437 210 695 239">5-5. Amount of solder</p> <p data-bbox="520 244 1463 336">Excessive solder will induce higher tensile force in chip capacitors when temperature changes and it may result in chip cracking. In sufficient solder may detach the capacitors from the P.C.board.</p> <hr/> <div data-bbox="496 389 619 456">Excessive solder</div> <div data-bbox="678 383 1086 490">  </div> <div data-bbox="1118 378 1410 468">Higher tensile force in chip capacitors to cause crack</div> <hr/> <div data-bbox="496 562 612 591">Adequate</div> <div data-bbox="678 510 1257 629">  </div> <hr/> <div data-bbox="496 696 628 763">Insufficient solder</div> <div data-bbox="678 689 1086 786">  </div> <div data-bbox="1118 669 1410 786">Low robustness may cause contact failure or chip capacitors come off the P.C.board.</div> <hr/> <p data-bbox="437 857 647 887">5-6. Sn-Zn solder</p> <p data-bbox="464 891 1155 954">Sn-Zn solder affects product reliability. Please contact TDK in advance when utilize Sn-Zn solder.</p> <p data-bbox="437 987 863 1016">5-7. Countermeasure for tombstone</p> <p data-bbox="464 1021 1449 1211">The misalignment between the mounted positions of the capacitors and the land patterns should be minimized. The tombstone phenomenon may occur especially the capacitors are mounted (in longitudinal direction) in the same direction of the reflow soldering. (Refer to JEITA RCR-2335C Annex A (Informative), Recommendations to prevent the tombstone phenomenon.)</p>


No.	Process	Condition																
6	Solder repairing	<p>Solder repairing is unavoidable, refer to below.</p> <p>6-1. Solder repair by solder iron</p> <p>1) Selection of the soldering iron tip</p> <p>Tip temperature of solder iron varies by its type, P.C.board material and solder land size. The higher the tip temperature, the quicker the operation. However, heat shock may cause a crack in the chip capacitors.</p> <p>Please make sure the tip temp. before soldering and keep the peak temp and time in accordance with following recommended condition.</p> <div><p>Manual soldering (Solder iron)</p></div> <table><tr><th colspan="4">Recommended solder iron condition (Sn-Pb Solder and Lead Free Solder)</th></tr><tr><th>Temp. (°C)</th><th>Duration (sec.)</th><th>Wattage (W)</th><th>Shape (mm)</th></tr><tr><td>280 max.</td><td>3 max.</td><td>20 max.</td><td>∅ 3.0 max.</td></tr></table> <p>* Please preheat the chip capacitors with the condition in 6-2 to avoid the thermal shock.</p> <p>2) Direct contact of the soldering iron with ceramic dielectric of chip capacitors may cause crack. Do not touch the ceramic dielectric and the terminations by solder iron.</p> <p>3) It is not recommended to reuse dismantled capacitors.</p> <p>6-2. Avoiding thermal shock</p> <p>Preheating condition</p> <table><tr><th>Soldering</th><th>Temp. (°C)</th></tr><tr><td>Manual soldering</td><td>$\Delta T \leq 130$</td></tr></table>	Recommended solder iron condition (Sn-Pb Solder and Lead Free Solder)				Temp. (°C)	Duration (sec.)	Wattage (W)	Shape (mm)	280 max.	3 max.	20 max.	∅ 3.0 max.	Soldering	Temp. (°C)	Manual soldering	$\Delta T \leq 130$
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Temp. (°C)	Duration (sec.)	Wattage (W)	Shape (mm)															
280 max.	3 max.	20 max.	∅ 3.0 max.															
Soldering	Temp. (°C)																	
Manual soldering	$\Delta T \leq 130$																	

No.	Process	Condition
7	Cleaning	<p>1) If an unsuitable cleaning fluid is used, flux residue or some foreign articles may stick to chip capacitors surface to deteriorate especially the insulation resistance.</p> <p>2) If cleaning condition is not suitable, it may damage the chip capacitors.</p> <p>2)-1. Insufficient washing</p> <p>(1) Terminal electrodes may corrode by Halogen in the flux.</p> <p>(2) Halogen in the flux may adhere on the surface of capacitors, and lower the insulation resistance.</p> <p>(3) Water soluble flux has higher tendency to have above mentioned problems (1) and (2).</p> <p>2)-2. Excessive washing</p> <p>When ultrasonic cleaning equipment is used, excessive ultrasonic power or direct vibration transfer to a printed wiring board may generate a resonant vibration in the board. This may cause a crack in a capacitor or its solder joints to the board and degradation in the terminal strength of the capacitor. In order to avoid this, the following cleaning conditions are recommended.</p> <p style="text-align: center;">Power : 20 W/l max. Frequency : 40 kHz max. Washing time : 5 minutes max.</p> <p>2)-3. If the cleaning fluid is contaminated, density of Halogen increases, and it may bring the same result as insufficient cleaning.</p>
8	Coating and molding of the P.C.board	<p>1) This product contains Ag (Silver) as part of the middle layer of termination. To avoid electromigration of Ag under high temperature and humidity, and failures caused by corrosive gas, chip capacitors on P.C boards should be protected by moisture proof-sealing.</p> <p>2) When the P.C.board is coated, please verify the quality influence on the product.</p> <p>3) Please verify carefully that there is no harmful decomposing or reaction gas emission during curing which may damage the chip capacitors.</p> <p>4) Please verify the curing temperature.</p>

No.	Process	Condition
9	<p>Handling after chip mounted</p> <p>⚠ Caution</p>	<p>1) Please pay attention not to bend or distort the P.C.board after soldering in handling otherwise the chip capacitors may crack.</p> <div data-bbox="486 291 1460 571"></div> <p>2) Printed circuit board cropping should not be carried out by hand, but by using the proper tooling. Printed circuit board cropping should be carried out using a board cropping jig as shown in the following figure or a board cropping apparatus to prevent inducing mechanical stress on the board.</p> <p>(1)Example of a board cropping jig</p> <p>Recommended example: The board should be pushed from the back side, close to the cropping jig so that the board is not bent and the stress applied to the capacitor is compressive.</p> <p>Unrecommended example: If the pushing point is far from the cropping jig and the pushing direction is from the front side of the board, large tensile stress is applied to the capacitor, which may cause cracks.</p> <div data-bbox="470 1030 1444 1299"></div>

No.	Process	Condition																	
9	Handling after chip mounted  Caution	<p>(2)Example of a board cropping machine</p> <p>An outline of a printed circuit board cropping machine is shown below. The top and bottom blades are aligned with one another along the lines with the V-grooves on printed circuit board when cropping the board.</p> <p>Unrecommended example: Misalignment of blade position between top and bottom, right and left, or front and rear blades may cause a crack in the capacitor.</p> <div><div><p>Outline of machine</p></div><div><p>Principle of operation</p></div><div><p>Cross-section diagram</p></div></div> <table><tr><th rowspan="2">Recommended</th><th colspan="3">Unrecommended</th></tr><tr><th>Top-bottom misalignment</th><th>Left-right misalignment</th><th>Front-rear misalignment</th></tr><tr><td><p>Top blade</p></td><td><p>Top blade</p></td><td><p>Top blade</p></td><td><p>Top blade</p></td></tr></table> <p>3) When functional check of the P.C.board is performed, check pin pressure tends to be adjusted higher for fear of loose contact. But if the pressure is excessive and bend the P.C.board, it may crack the chip capacitors or peel the terminations off. Please adjust the check pins not to bend the P.C.board.</p> <table><tr><th>Item</th><th>Not recommended</th><th>Recommended</th></tr><tr><td>Board bending</td><td></td><td></td></tr></table>	Recommended	Unrecommended			Top-bottom misalignment	Left-right misalignment	Front-rear misalignment	<p>Top blade</p> 	<p>Top blade</p> 	<p>Top blade</p> 	<p>Top blade</p> 	Item	Not recommended	Recommended	Board bending		
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Item	Not recommended	Recommended																	
Board bending																			

No.	Process	Condition
10	Handling of loose chip capacitors	<p>1) If dropped the chip capacitors may crack. Once dropped do not use it. Especially, the large case sized chip capacitors are tendency to have cracks easily, so please handle with care.</p>  <p>2) Piling the P.C.board after mounting for storage or handling, the corner of the P.C. board may hit the chip capacitors of another board to cause crack.</p> 
11	Capacitance aging	<p>The capacitors (Class 2) have aging in the capacitance. They may not be used in precision time constant circuit. In case of the time constant circuit, the evaluation should be done well.</p>
12	Estimated life and estimated failure rate of capacitors	<p>As per the estimated life and the estimated failure rate depend on the temperature and the voltage. This can be calculated by the equation described in JEITA RCR-2335C Annex F (Informative) Calculation of the estimated lifetime and the estimated failure rate (Voltage acceleration coefficient : 3 multiplication rule, Temperature acceleration coefficient : 10°C rule) The failure rate can be decreased by reducing the temperature and the voltage but they will not be guaranteed.</p>

No.	Process	Condition
13	Caution during operation of equipment	<p>1) A capacitor shall not be touched directly with bare hands during operation in order to avoid electric shock. Electric energy held by the capacitor may be discharged through the human body when touched with a bare hand. Even when the equipment is off, a capacitor may stay charged. The capacitor should be handled after being completely discharged using a resistor.</p> <p>2) The terminals of a capacitor shall not be short-circuited by any accidental contact with a conductive object. A capacitor shall not be exposed to a conductive liquid such as an acid or alkali solution. A conductive object or liquid, such as acid and alkali, between the terminals may lead to the breakdown of a capacitor due to short circuit</p> <p>3) Confirm that the environment to which the equipment will be exposed during transportation and operation meets the specified conditions. Do not to use the equipment in the following environments.</p> <p>(1) Environment where a capacitor is spattered with water or oil (2) Environment where a capacitor is exposed to direct sunlight (3) Environment where a capacitor is exposed to Ozone, ultraviolet rays or radiation (4) Environment where a capacitor exposed to corrosive gas(e.g. hydrogen sulfide, sulfur dioxide, chlorine. ammonia gas etc.) (5) Environment where a capacitor exposed to vibration or mechanical shock exceeding the specified limits. (6) Atmosphere change with causes condensation</p>
14	Others  Caution	<p>The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.</p> <p>The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet. If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or conditions set forth in this specification, please contact us.</p> <p>(1) Aerospace/Aviation equipment (2) Transportation equipment (cars, electric trains, ships, etc.) (3) Medical equipment (Excepting Pharmaceutical Affairs Law classification Class1, 2) (4) Power-generation control equipment (5) Atomic energy-related equipment (6) Seabed equipment (7) Transportation control equipment (8) Public information-processing equipment (9) Military equipment (10) Electric heating apparatus, burning equipment (11) Disaster prevention/crime prevention equipment (12) Safety equipment (13) Other applications that are not considered general-purpose applications</p> <p>When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.</p>

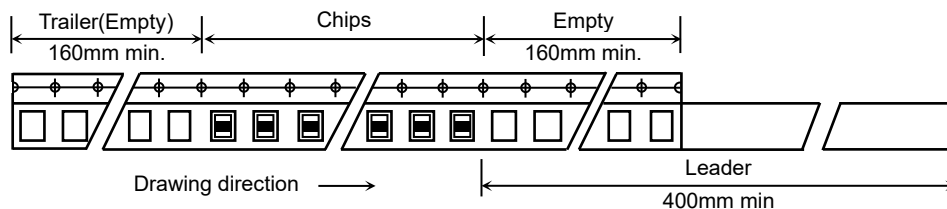
14. TAPE PACKAGING SPECIFICATION

1. CONSTRUCTION AND DIMENSION OF TAPING

1-1. Dimensions of carrier tape

Dimensions of plastic tape shall be according to Appendix 3,4.

1-2. Empty part and leader of taping

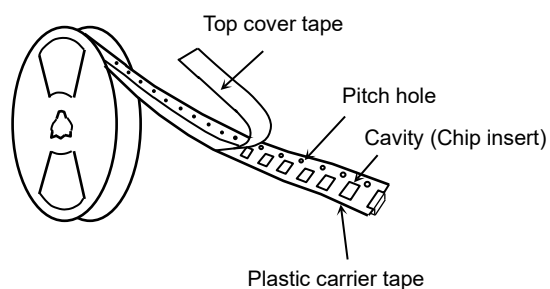


1-3. Dimensions of reel

Dimensions of \varnothing 178 reel shall be according to Appendix 5.

Dimensions of \varnothing 330 reel shall be according to Appendix 6.

1-4. Structure of taping



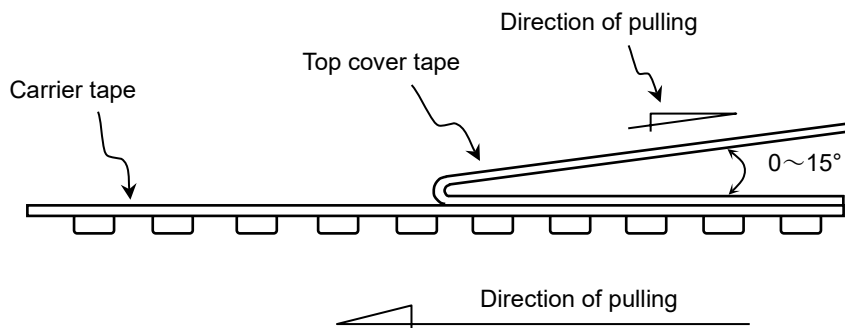
2. CHIP QUANTITY

Please refer to detail page on TDK web.

3. PERFORMANCE SPECIFICATIONS

3-1. Fixing peeling strength (top tape)

$0.05 < \text{Peeling strength} < 0.7\text{N}$



3-2. Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

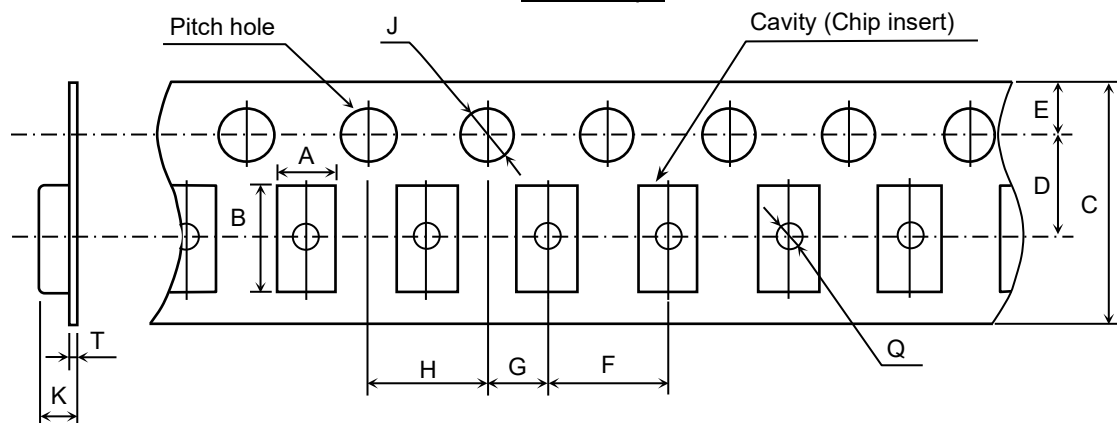
3-3. The missing of components shall be less than 0.1%

3-4. Components shall not stick to fixing tape.

3-5. When removing the cover tape, there shall not be difficulties by unfitting clearance gap, burrs and crushes of cavities. Also the sprocket holes shall not be covered by absorbing dust into the suction nozzle.

Appendix 3

Plastic Tape



(Unit : mm)

Symbol	A	B	C	D	E	F
Case size						
C3225 [CC1210]	(2.90)	(3.60)	12.00 ± 0.30	5.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10

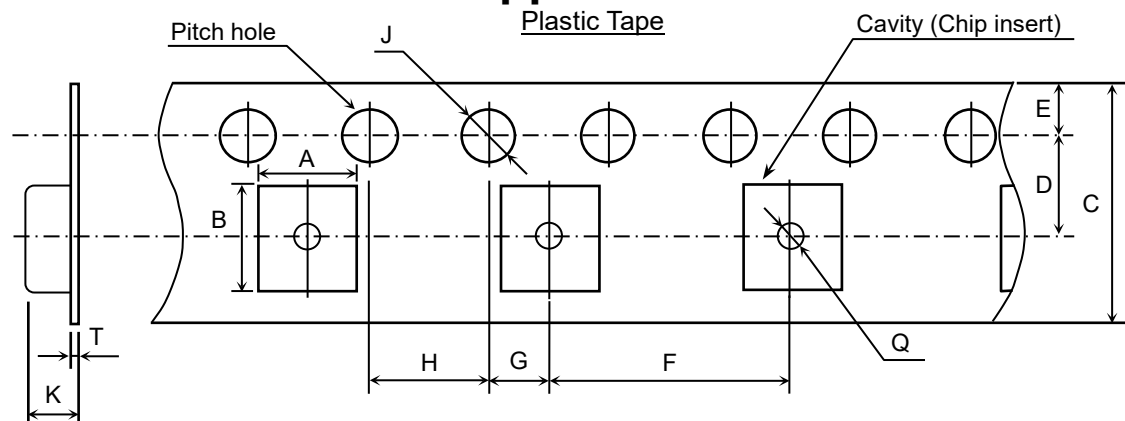
Symbol	G	H	J	K	T	Q
Case size						
C3225 [CC1210]	2.00 ± 0.05	4.00 ± 0.10	∅ 1.50 ^{+0.10} ₀	3.40 max.	0.60 max.	∅ 0.50 min.

() Reference value.

Exceptionally no hole in the cavity is applied. Please inquire if hole in cavity is mandatory.

Appendix 4

Plastic Tape



(Unit : mm)

Symbol	A	B	C	D	E	F
Case size						
C4520 [CC1808]	(2.50)	(5.10)	12.0 ± 0.30	5.50 ± 0.05	1.75 ± 0.10	8.00 ± 0.10
C4532 [CC1812]	(3.60)	(4.90)				

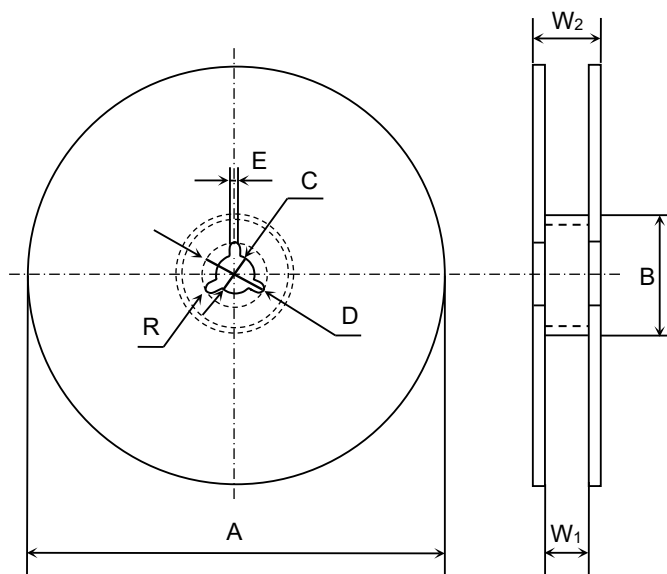
Symbol	G	H	J	K	T	Q
Case size						
C4520 [CC1808]	2.00 ± 0.05	4.00 ± 0.10	∅ 1.50 ^{+0.10} ₀	6.50 max.	0.60 max.	∅ 1.50 min.
C4532 [CC1812]						

() Reference value.

Exceptionally no hole in the cavity is applied. Please inquire if hole in cavity is mandatory.

Appendix 5

Dimensions of reel (Material : Polystyrene)

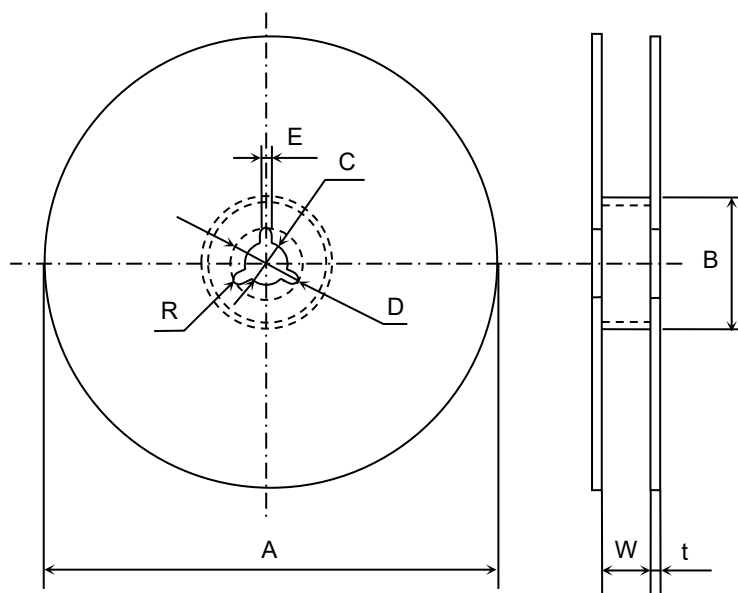


(Unit : mm)

Symbol	A	B	C	D	E	W ₁
Dimension	$\varnothing 178 \pm 2.0$	$\varnothing 60 \pm 2.0$	$\varnothing 13 \pm 0.5$	$\varnothing 21 \pm 0.8$	2.0 ± 0.5	13.0 ± 0.3
Symbol	W ₂	R				
Dimension	17.0 ± 1.4	1.0				

Appendix 6

Dimensions of reel (Material : Polystyrene)



(Unit : mm)

Symbol	A	B	C	D	E	W
Dimension	$\varnothing 382 \text{ max.}$ (Nominal $\varnothing 330$)	$\varnothing 50 \text{ min.}$	$\varnothing 13 \pm 0.5$	$\varnothing 21 \pm 0.8$	2.0 ± 0.5	14.0 ± 1.5
Symbol	t	R				
Dimension	2.0 ± 0.5	1.0				